

OCXOVST - 5.0V OCXO CMOS Output Stratum 3

Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass	
Base	Metal Case	Co	7440-48-4	423.000	21.97	
	Metal Case	Fe	7439-89-6	1.000	0.05	
	Metal Case	Ni	7440-02-0	681.500	35.40	
	Metal Case	Pb	7439-92-1	0.470	0.02	
	Metal Case	Si	7440-21-3	23.500	1.22	
	Metal Case	Sn	7440-31-5	23.500	1.22	
	Metal Case	Fe	7439-89-6	1.000	0.05	
	Metal Case	Ni	7440-02-0	681.500	35.40	
	Metal Case	Co	7440-48-4	42.300	2.20	
	Metal Case	Sn	7440-31-5	23.500	1.22	
	Metal Case	Pb	7439-92-1	0.470	0.02	
	Metal Case	Si	7440-21-3	23.500	1.22	
	Capacitors	Ceramic	Al2O3	1344-28-1	108.000	31.35
		Ceramic capacitor chip	Al2O3	1344-28-1	112.500	32.66
Ceramic capacitor chip		Ni	7440-02-0	11.500	3.34	
Ceramic capacitor chip		Sn	7440-31-5	100.000	29.03	
Ceramic capacitor chip		Cu	7440-50-8	12.500	3.63	
Crystal	Plating	Ag	7440-22-4	42.000	77.78	
	Plating	Cu	7440-50-8	1.200	2.22	
	Plating	Ni	7440-02-0	1.200	2.22	
	Plating	Sn	7440-31-5	9.600	17.78	
Crystal Lid	Metal Cap	Fe	7439-89-6	38.250	51.00	
	Metal Cap	Ni	7440-02-0	19.500	26.00	
	Metal Cap	Sn	7440-31-5	11.250	15.00	
	Metal Cap	Co	7440-48-4	4.500	6.00	
	Metal Cap	Au	7440-57-5	1.500	2.00	
Die	IC	(C7H8O.CH2O)x	25053-96-7	15.600	6.50	
	IC	Ag	7440-22-4	2.400	1.00	
	IC	Au	7440-57-5	1.200	0.50	
	IC	Cu	7440-50-8	30.000	12.50	
	IC	Fe	7439-89-6	1.200	0.50	
	IC	Si	7440-21-3	3.600	1.50	
	IC	SiO2	14808-60-7	50.400	21.00	
	IC	Sn	7440-31-5	15.600	6.50	
	IC	SiO2	14808-60-7	50.400	21.00	
	IC	(C7H8O.CH2O)x	25053-96-7	15.600	6.50	
	IC	Cu	7440-50-8	30.000	12.50	
	IC	Si	7440-21-3	3.600	1.50	
	IC	Sn	7440-31-5	15.600	6.50	
	IC	Ag	7440-22-4	2.400	1.00	
	IC	Au	7440-57-5	1.200	0.50	
	IC	Fe	7439-89-6	1.200	0.50	

Material Composition Data



Product: OCXOVST

Page 2

Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
Epoxy	Conducting Epoxy	Epoxy	129915-35-1	18.000	100.00
Expoxy attach	Silver epoxy	Other		18.000	30.00
	Silver epoxy	Ag	7440-22-4	42.000	70.00
Lid	Cap	Fe	7439-89-6	1.000	3.85
	Cap	Ni	7440-02-0	25.000	96.15
Lids	Metal Cap	Fe	7439-89-6	1.000	3.85
	Metal Cap	Ni	7440-02-0	25.000	96.15
PCB	Epoxy	Au	7440-57-5	23.400	1.50
	Epoxy	Cu	7440-50-8	109.200	7.00
	Epoxy	Epoxy	129915-35-1	624.000	40.00
	Epoxy	Ni	7440-02-0	23.400	1.50
	Epoxy	Other		624.000	40.00
	Epoxy	Ni	7440-02-0	23.400	1.50
	Epoxy	Cu	7440-50-8	109.200	7.00
	Epoxy	Au	7440-57-5	23.400	1.50
Quartz lid	Metal Cap	Au	7440-57-5	1.500	2.00
	Metal Cap	Co	7440-48-4	4.500	6.00
	Metal Cap	Fe	7439-89-6	38.250	51.00
	Metal Cap	Ni	7440-02-0	19.500	26.00
	Metal Cap	Sn	7440-31-5	11.250	15.00
Resistor	Ceramic	Al2O3	1344-28-1	54.000	90.00
	Ceramic	Cu	7440-50-8	0.600	1.00
	Ceramic	Ni	7440-02-0	0.600	1.00
	Ceramic	Sn	7440-31-5	4.800	8.00
Resistors	Ceramic chip	Al2O3	1344-28-1	54.000	90.00
	Ceramic chip	Ni	7440-02-0	0.600	1.00
	Ceramic chip	Sn	7440-31-5	4.800	8.00
	Ceramic chip	Cu	7440-50-8	0.600	1.00
Resonator	Quartz	SiO2	14808-60-7	0.800	6.25
	Quartz	Cr	7440-47-3	0.500	3.91
	Quartz	Au	7440-57-5	1.500	11.72
	Quartz crystal	Au	7440-57-5	1.500	11.72
	Quartz crystal	Cr	7440-47-3	0.500	3.91
	Quartz crystal	SiO2	14808-60-7	8.000	62.50
Resonator Housing	Ceramic	Al2O3	1344-28-1	112.500	45.00
	Ceramic	Al2O3	1344-28-1	112.500	45.00
	Ceramic	W	7440-33-7	3.750	1.50
	Ceramic	Ni	7440-02-0	2.500	1.00
	Ceramic	Au	7440-57-5	6.250	2.50
	Plating	Au	7440-57-5	6.250	2.50
	Plating	Ni	7440-02-0	2.500	1.00

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Product: OCXOVST

Page 3

Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
Resonator Housing	Plating	W	7440-33-7	3.750	1.50
Solder joint	Solder	Ag	7440-22-4	1.000	1.00
	Solder	Cu	7440-50-8	0.500	0.50
	Solder	Sn	7440-31-5	48.500	48.50
	Solder	Sn	7440-31-5	48.500	48.50
	Solder	Cu	7440-50-8	0.500	0.50
	Solder	Ag	7440-22-4	1.000	1.00
Total Mass:				4886.540 mg	

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